ADHETRON®
Masterpiece of Adhesives

TECHNICAL DATA SHEET

EP 2669 THERMALLY CONDUCTIVE EPOXY RESIN

PRODUCT DESCRIPTION

EP2669 is a high performance electrical insulating, thermally conductive epoxy adhesive, potting and encapsulation compound. A combination of excellent characteristics of thermal conductivity and low coefficient expansion. EP2669 is a two component room temperature cure system which has an advantage about storage, shipping and curing for heat sensitive components against one component systems. Typical applications are; heat sink bonding, casting of magnetic coils, encapsulation of heat emitting components, transformers and all kind of heat sensitive application.

CURING PROPERTIES

25^{0}C	For maximum and heat resistant properties, 4 hours at 150° C post cure recommended.
24hr.	

UNCURED PROPERTIES

Color	Black
Viscosity (Catalyzed, 25^{0}C, cps)	70,000
Specific Gravity	2,5
Mixing Ratio (by weight)	100:8 (PartA:PartB)

Our data sheets have been compiled to the best of our knowledge. The information included in our data sheets is exclusive information for the tended user and describes characteristics, with no declaration of commitment. We recommend trials in order to confirm that our products satisfy the particular application requirements. For an additional technical consultation, please contact our RD department.
Adhetron is a brand of Pulsar Chem. Industry and Trade Co. INC.

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● CURED PROPERTIES

Property	Value
Tensile Strength (N/mm^2)	58,20
Compressive Strength (N/mm^2)	512
Flexural Strength (N/mm^2)	92,30
Thermal Conductivity	
W/mK (BTU/ (HR) (FT^2) (°F/In)	0,7 4.76
Thermal Expansion Coefficient (/°C)	15 x 10^{-6}
Thermal Deflection (°C)	135
Water Absorption (7 Days)	Less than 0.1%
Volume Resistivity (ohm-cm @ 25°C) (ohm-cm @ 150°C)	4.5 x 10^{14} 1.3 x 10^{12}
Dielectric Constant (10^2 to 10^{10} Hz)	4.7
Dissipation Factor (10^2 to 10^8 Hz)	Less than 0.01
Dielectric Strength (Volts/mil)	460
Operating Temperature	-75°C +130°C

● INSTRUCTIONS FOR USE

The surfaces should be free of dust, oil and other dirt in order to optain an optimal efficient bond.

The components A and B have to be homogenised well, weight out in mixing ration and homogenised with each other for min. 2 minutes.
From now, the pot life time starts and the adhesive has to be applied rapidly. The mixed adhesive should not be applied after the pot life time. It is useful to mix only this quantity of adhesive you can apply during the pot life time.

For curing heat must be applied. In some cases they will cure even at room temperature. But higher temperature will reduce the curing time. For detailed curing information, please look into the technical data sheet.

Shelf life: Store in original, unopened containers for 12 months at room temperature

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